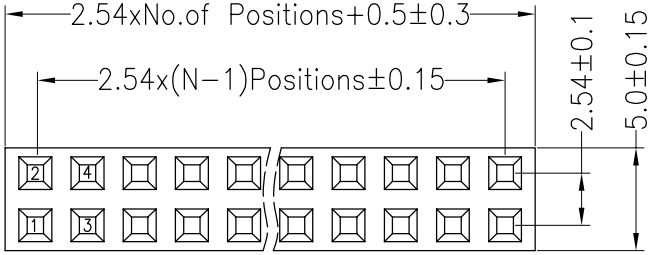
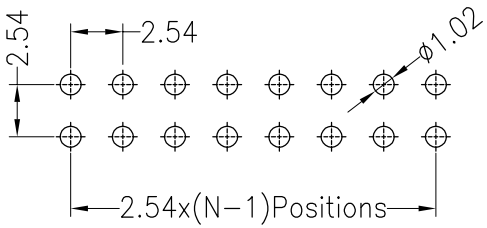
HSF RoHS

SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



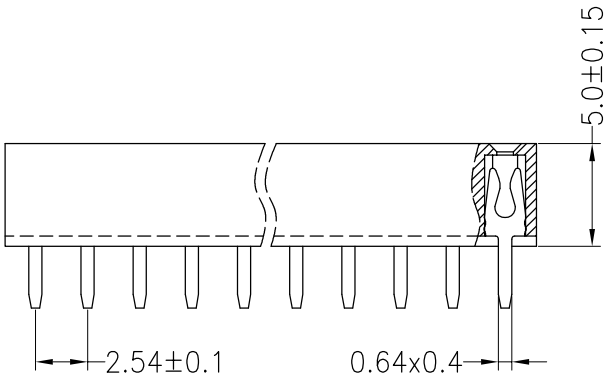
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

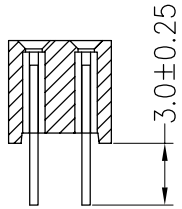


Ordering Information

2250 02 XX X N XX S Y X 0X

- No.of Pins Per Row 2~40
- Insulator Material Option
  - A=BK−PBT
  - C=BK−PA6T
  - D=BK−PA46
  - E=BK−PA9T
  - F=BK−LCP
- Contact Plating
  - G1:Gold Flash
  - G3:2U" Gold
  - G4:5U" Gold
  - G5:10U" Gold
  - G6:15U" Gold
  - S0:Gold Flash/Tin
  - SN:Tin
- Packing
  - 0=PE Bag
  - T=Tube





REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2021.06.04	NEW DRAWING	

OPERATION		DRAW	Liu Miao	21.06.04	SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	225002XXXNXXSYX0X
TITLE:	2.54PF H5.0mm 2xNpin 180° DIP